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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	32256
Number of Logic Elements/Cells	-
Total RAM Bits	294912
Number of I/O	586
Number of Gates	2000000
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 85°C (TA)
Package / Case	896-BGA
Supplier Device Package	896-FBGA (31x31)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ax2000-fg896i

Figure 1-8 • AX Routing Structures

Global Resources

Each family member has three types of global signals available to the designer: HCLK, CLK, and GCLR/GPSET. There are four hardwired clocks (HCLK) per device that can directly drive the clock input of each R-cell. Each of the four routed clocks (CLK) can drive the clock, clear, preset, or enable pin of an R-cell or any input of a C-cell (Figure 1-3 on page 1-2).

Global clear (GCLR) and global preset (GPSET) drive the clear and preset inputs of each R-cell as well as each I/O Register on a chip-wide basis at power-up.

Each HCLK and CLK has an associated analog PLL (a total of eight per chip). Each embedded PLL can be used for clock delay minimization, clock delay adjustment, or clock frequency synthesis. The PLL is capable of operating with input frequencies ranging from 14 MHz to 200 MHz and can generate output frequencies between 20 MHz and 1 GHz. The clock can be either divided or multiplied by factors ranging from 1 to 64. Additionally, multiply and divide settings can be used in any combination as long as the resulting clock frequency is between 20 MHz and 1 GHz. Adjacent PLLs can be cascaded to create complex frequency combinations.

The PLL can be used to introduce either a positive or a negative clock delay of up to 3.75 ns in 250 ps increments. The reference clock required to drive the PLL can be derived from three sources: external input pad (either single-ended or differential), internal logic, or the output of an adjacent PLL.

Low Power (LP) Mode

The AX architecture was created for high-performance designs but also includes a low power mode (activated via the LP pin). When the low power mode is activated, I/O banks can be disabled (inputs disabled, outputs tristated), and PLLs can be placed in a power-down mode. All internal register states are maintained in this mode. Furthermore, individual I/O banks can be configured to opt out of the LP mode, thereby giving the designer access to critical signals while the rest of the chip is in low power mode.

The power can be further reduced by providing an external voltage source (V_{PUMP}) to the device to bypass the internal charge pump (See "Low Power Mode" on page 2-106 for more information).

Using the Differential I/O Standards

Differential I/O macros should be instantiated in the netlist. The settings for these I/O standards cannot be changed inside Designer. Note that there are no tristated or bidirectional I/O buffers for differential standards.

Using the Voltage-Referenced I/O Standards

Using these I/O standards is similar to that of single-ended I/O standards. Their settings can be changed in Designer.

Using DDR (Double Data Rate)

In Double Data Rate mode, new data is present on every transition of the clock signal. Clock and data lines have identical bandwidth and signal integrity requirements, making it very efficient for implementing very high-speed systems.

To implement a DDR, users need to:

1. Instantiate an input buffer (with the required I/O standard)
2. Instantiate the DDR_REG macro (Figure 2-6)
3. Connect the output from the Input buffer to the input of the DDR macro

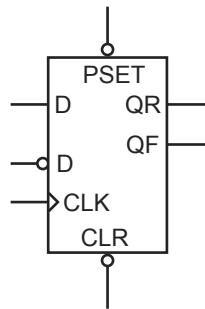


Figure 2-6 • DDR Register

Macros for Specific I/O Standards

There are different macro types for any I/O standard or feature that determine the required VCCI and VREF voltages for an I/O. The generic buffer macros require the LVTTTL standard with slow slew rate and 24 mA-drive strength. LVTTTL can support high slew rate but this should only be used for critical signals.

Most of the macro symbols represent variations of the six generic symbol types:

- CLKBUF: Clock Buffer
- HCLKBUF: Hardwired Clock Buffer
- INBUF: Input Buffer
- OUTBUF: Output Buffer
- TRIBUF: Tristate Buffer
- BIBUF: Bidirectional Buffer

Other macros include the following:

- Differential I/O standard macros: The LVDS and LVPECL macros either have a pair of differential inputs (e.g. INBUF_LVDS) or a pair of differential outputs (e.g. OUTBUF_LVPECL).
- Pull-up and pull-down variations of the INBUF, BIBUF, and TRIBUF macros. These are available only with TTL and LVCMOS thresholds. They can be used to model the behavior of the pull-up and pull-down resistors available in the architecture. Whenever an input pin is left unconnected, the output pin will either go high or low rather than unknown. This allows users to leave inputs unconnected without having the negative effect on simulation of propagating unknowns.
- DDR_REG macro. It can be connected to any I/O standard input buffers (i.e. INBUF) to implement a double data rate register. Designer software will map it to the I/O module in the same way it maps the other registers to the I/O module.

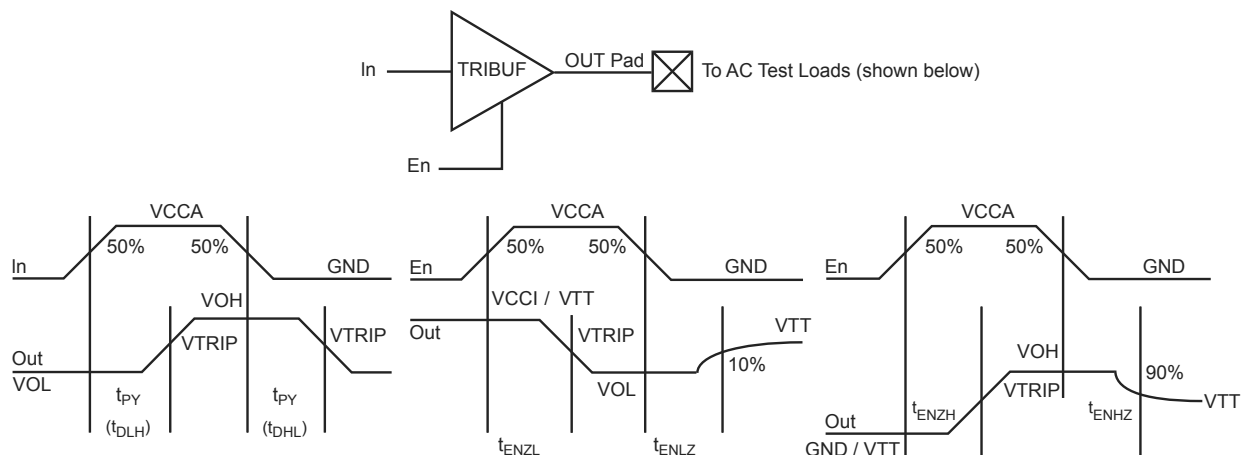


Figure 2-10 • Output Buffer Delays

Table 2-22 • 3.3 V LVTTTL I/O Module

Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C (continued)

		–2 Speed		–1 Speed		Std Speed		
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	Units
LVTTTL Output Drive Strength =3 (16 mA) / High Slew Rate								
t _{DP}	Input Buffer		1.68		1.92		2.26	ns
t _{PY}	Output Buffer		3.12		3.56		4.18	ns
t _{ENZL}	Enable to Pad Delay through the Output Buffer—Z to Low		3.54		4.04		4.75	ns
t _{ENZH}	Enable to Pad Delay through the Output Buffer—Z to High		2.78		3.17		3.72	ns
t _{ENLZ}	Enable to Pad Delay through the Output Buffer—Low to Z		1.91		1.93		1.93	ns
t _{ENHZ}	Enable to Pad Delay through the Output Buffer—High to Z		2.58		2.59		2.60	ns
t _{IOCLKQ}	Sequential Clock-to-Q for the I/O Input Register		0.67		0.77		0.90	ns
t _{IOCLKY}	Clock-to-output Y for the I/O Output Register and the I/O Enable Register		0.67		0.77		0.90	ns
t _{SUD}	Data Input Set-Up		0.23		0.27		0.31	ns
t _{SUE}	Enable Input Set-Up		0.26		0.30		0.35	ns
t _{HD}	Data Input Hold		0.00		0.00		0.00	ns
t _{HE}	Enable Input Hold		0.00		0.00		0.00	ns
t _{CPWHL}	Clock Pulse Width High to Low	0.39		0.39		0.39		ns
t _{CPWLH}	Clock Pulse Width Low to High	0.39		0.39		0.39		ns
t _{WASYN}	Asynchronous Pulse Width	0.37		0.37		0.37		ns
t _{REASYN}	Asynchronous Recovery Time		0.13		0.15		0.17	ns
t _{HASYN}	Asynchronous Removal Time		0.00		0.00		0.00	ns
t _{CLR}	Asynchronous Clear-to-Q		0.23		0.27		0.31	ns
t _{PRESET}	Asynchronous Preset-to-Q		0.23		0.27		0.31	ns

3.3 V PCI, 3.3 V PCI-X

Peripheral Component Interface for 3.3 V standard specifies support for both 33 MHz and 66 MHz PCI bus applications. It uses an LVTTTL input buffer and a push-pull output buffer. The input and output buffers are 5 V tolerant with the aid of external components. Axcelerator 3.3 V PCI and 3.3 V PCI-X buffers are compliant with the PCI Local Bus Specification Rev. 2.1.

The PCI Compliance Specification requires the clamp diodes to be able to withstand for 11 ns, -3.5 V in undershoot, and 7.1 V in overshoot.

Table 2-33 • DC Input and Output Levels

	VIL		VIH		VOL	VOH	IOL	IOH
	Min., V	Max., V	Min., V	Max., V	Max., V	Min., V	mA	mA
PCI	-0.3	0.3 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			
PCI-X	-0.5	0.35 VCCI	0.5 VCCI	VCCI + 0.5	(per PCI specification)			

AC Loadings

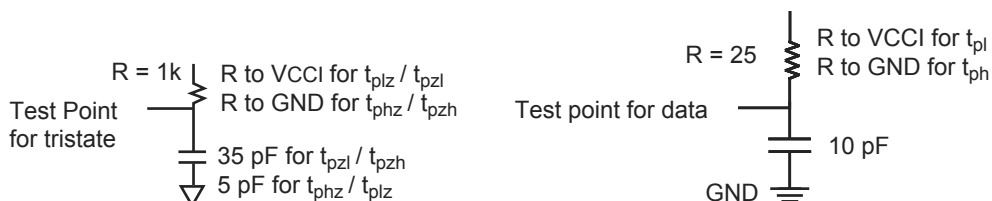


Figure 2-18 • AC Test Loads

Table 2-34 • AC Waveforms, Measuring Points, and Capacitive Loads

Input Low (V)	Input High (V)	Measuring Point* (V)	VREF (typ) (V)	C _{load} (pF)
(Per PCI Spec and PCI-X Spec)			N/A	10

Note: * Measuring Point = VTRIP

PLLCLK and PLLHCLK

PLLCLK (PLLHCLK) is used to drive global resource CLK (HCLK) from a PLL (Figure 2-44).

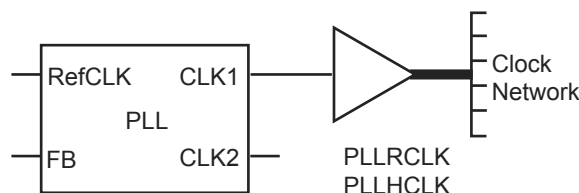


Figure 2-44 • PLLRCLK and PLLHCLK

Using Global Resources with PLLs

Each global resource has an associated PLL at its root. For example, PLLA can drive HCLKA, PLLE can drive CLKE, etc. (Figure 2-45).

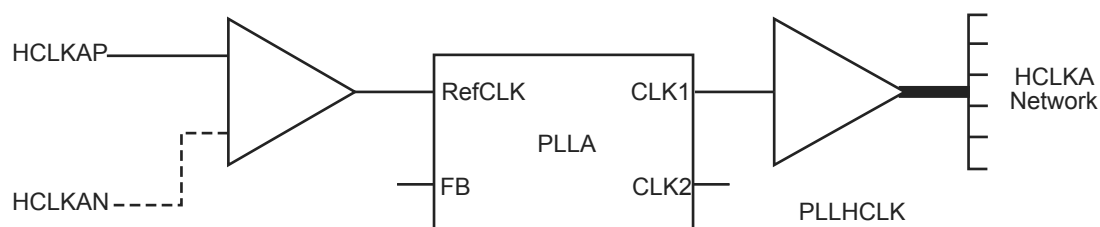


Figure 2-45 • Example of HCLKA Driven from a PLL with External Clock Source

In addition, each clock pin of the package can be used to drive either its associated global resource or PLL. For example, package pins CLKEP and CLKEN can drive either the RefCLK input of PLLE or CLKE.

There are two macros required when interfacing the embedded PLLs with the global resources: PLLINT and PLLOUT.

PLLINT

This macro is used to drive the RefCLK input of the PLL internally from user signals.

PLLOUT

This macro is used to connect either the CLK1 or CLK2 output of a PLL to the regular routing network (Figure 2-46).

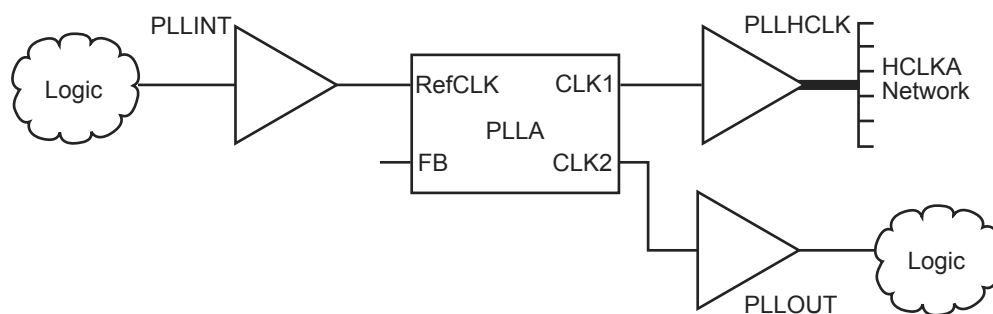


Figure 2-46 • Example of PLLINT and PLLOUT Usage

Table 2-102 • Sixteen FIFO Blocks Cascaded
Worst-Case Commercial Conditions VCCA = 1.425 V, VCCI = 3.0 V, T_J = 70°C

		–2 Speed		–1 Speed		Std Speed		Units
Parameter	Description	Min.	Max.	Min.	Max.	Min.	Max.	
FIFO Module Timing								
t _{WSU}	Write Setup		16.32		18.60		21.86	ns
t _{WHD}	Write Hold		0.00		0.00		0.00	ns
t _{WCKH}	WCLK High		0.75		0.75		0.75	ns
t _{WCKL}	WCLK Low		13.40		13.40		13.40	ns
t _{WCKP}	Minimum WCLK Period	14.15		14.15		14.15		ns
t _{RSU}	Read Setup		17.16		19.54		22.97	ns
t _{RHD}	Read Hold		0.00		0.00		0.00	ns
t _{RCKH}	RCLK High		0.73		0.73		0.73	ns
t _{RCKL}	RCLK Low		14.41		14.41		14.41	ns
t _{RCKP}	Minimum RCLK period	15.14		15.14		15.14		ns
t _{CLRHF}	Clear High		0.00		0.00		0.00	ns
t _{CLR2FF}	Clear-to-flag (EMPTY/FULL)		1.92		2.18		2.57	ns
t _{CLR2AF}	Clear-to-flag (AEMPTY/AFULL)		4.39		5.00		5.88	ns
t _{CK2FF}	Clock-to-flag (EMPTY/FULL)		2.13		2.42		2.85	ns
t _{CK2AF}	Clock-to-flag (AEMPTY/AFULL)		5.04		5.75		6.75	ns
t _{RCK2RD1}	RCLK-To-OUT (Pipelined)		12.08		13.76		16.17	ns
t _{RCK2RD2}	RCLK-To-OUT (Nonpipelined)		12.83		14.62		17.18	ns

Note: Timing data for these sixteen cascaded FIFO blocks uses a depth of 65,536. For all other combinations, use Microsemi's timing software.

Building RAM and FIFO Modules

RAM and FIFO modules can be generated and included in a design in two different ways:

- Using the SmartGen Core Generator where the user defines the depth and width of the FIFO/RAM, and then instantiates this block into the design (refer to the *SmartGen*, *FlashROM*, *Analog System Builder*, and *Flash Memory System Builder* User's Guide for more information).
- The alternative is to instantiate the RAM/FIFO blocks manually, using inverters for polarity control and tying all unused data bits to ground.

Other Architectural Features

Low Power Mode

Although designed for high performance, the AX architecture also allows the user to place the device into a low power mode. Each I/O bank in an Axcelerator device can be configured individually, when in low power mode, to tristate all outputs, disable inputs, or both. The low power mode is activated by asserting the LP pin, which is grounded in normal operation.

While in the low power mode, the device is still fully functional and all internal logic states are preserved. This allows a user to disable all but a few signals and operate the part in a low-frequency, watchdog

throughout the fabric of the device and may be programmed by the user to thwart attempts to reverse engineer the device by attempting to exploit either the programming or probing interfaces. Both invasive and noninvasive attacks against an Axcelerator device that access or bypass these security fuses will destroy access to the rest of the device. (refer to the *Design Security in Nonvolatile Flash and Antifuse FPGAs* white paper).

Look for this symbol to ensure your valuable IP is protected with highest level of security in the industry.



Figure 2-69 • FuseLock Logo

To ensure maximum security in Axcelerator devices, it is recommended that the user program the device security fuse (SFUS). When programmed, the Silicon Explorer II testing probes are disabled to prevent internal probing, and the programming interface is also disabled. All JTAG public instructions are still accessible by the user.

For more information, refer to the *Implementation of Security in Actel Antifuse FPGAs* application note.

Global Set Fuse

The Global Set Fuse determines if all R-cells and I/O registers (InReg, OutReg, and EnReg) are either cleared or preset by driving the GCLR and GPSET inputs of all R-cells and I/O Registers (Figure 2-31 on page 2-58). Default setting is to clear all registers (GCLR = 0 and GPSET = 1) at device power-up. When the GBSETFUS option is checked during FUSE file generation, all registers are preset (GCLR = 1 and GPSET = 0). A local CLR or PRESET will take precedence over this setting. Both pins are pulled High during normal device operation. For use details, see the Libero IDE online help.

Silicon Explorer II Probe Interface

Silicon Explorer II is an integrated hardware and software solution that, in conjunction with the Designer tools, allows users to examine any of the internal nets (except I/O registers) of the device while it is operating in a prototype or a production system. The user can probe up to four nodes at a time without changing the placement and routing of the design and without using any additional device resources. Highlighted nets in Designer's ChipPlanner can be accessed using Silicon Explorer II in order to observe their real time values.

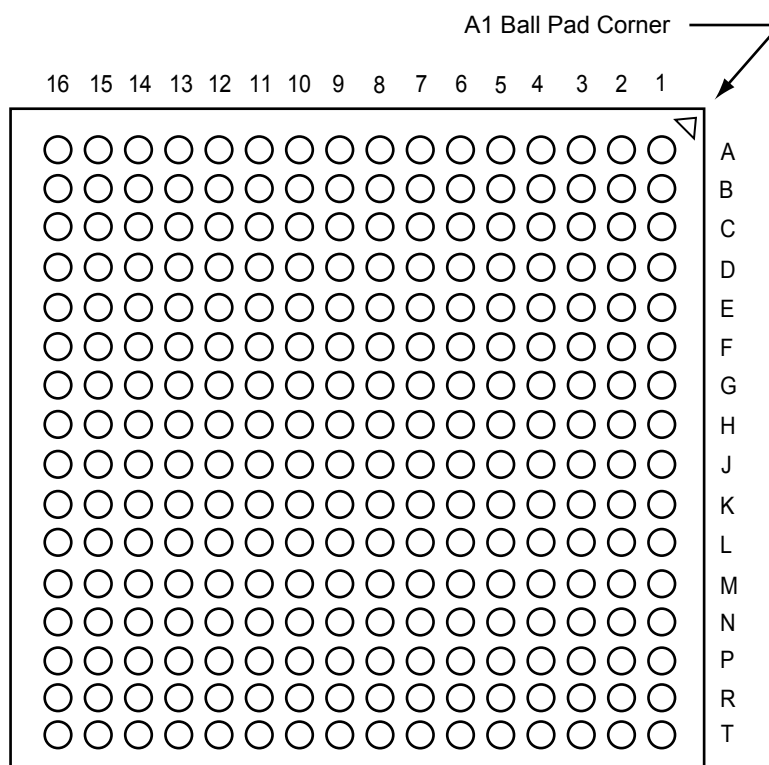
Silicon Explorer II's noninvasive method does not alter timing or loading effects, thus shortening the debug cycle. In addition, Silicon Explorer II does not require relayout or additional MUXes to bring signals out to external pins, which is necessary when using programmable logic devices from other suppliers. By eliminating multiple place-and-route program cycles, the integrity of the design is maintained throughout the debug process.

Each member of the Axcelerator family has four external pads: PRA, PRB, PRC, and PRD. These can be used to bring out four probe signals from the Axcelerator device (note that the AX125 only has two probe signals that can be observed: PRA and PRB). Each core tile has up to two probe signals. To disallow probing, the SFUS security fuse in the silicon signature has to be programmed (see "Special Fuses" on page 2-108).

Silicon Explorer II connects to the host PC using a standard serial port connector. Connections to the circuit board are achieved using a nine-pin D-Sub connector (Figure 1-9 on page 1-7). Once the design has been placed-and-routed, and the Axcelerator device has been programmed, Silicon Explorer II can be connected and the Explorer software can be launched.

Silicon Explorer II comes with an additional optional PC hosted tool that emulates an 18-channel logic analyzer. Four channels are used to monitor four internal nodes, and 14 channels are available to probe external signals. The software included with the tool provides the user with an intuitive interface that allows for easy viewing and editing of signal waveforms.

FG256



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

FG484	
AX500 Function	Pin Number
IO54PB2F5	H22
IO55NB2F5	L17
IO55PB2F5	K17
IO56NB2F5	K21
IO56PB2F5	K22
IO58NB2F5	L20
IO58PB2F5	K20
IO59NB2F5	L18
IO59PB2F5	K18
IO60NB2F5	M21
IO60PB2F5	L21
IO61NB2F5	L16
IO61PB2F5	K16
IO62NB2F5	M19
IO62PB2F5	L19
Bank 3	
IO63NB3F6	N16
IO63PB3F6	M16
IO64NB3F6	P22
IO64PB3F6	N22
IO65NB3F6	N20
IO65PB3F6	M20
IO66NB3F6	P21
IO66PB3F6	N21
IO67NB3F6	N18
IO67PB3F6	N19
IO68NB3F6	T22
IO68PB3F6	R22
IO69NB3F6	N17
IO69PB3F6	M17
IO70NB3F6	T21
IO70PB3F6	R21
IO71NB3F6	P18
IO71PB3F6	P19
IO72NB3F6	R20

FG484	
AX500 Function	Pin Number
IO72PB3F6	P20
IO73PB3F6	R19
IO74NB3F7	V21
IO74PB3F7	U21
IO75NB3F7	V22
IO75PB3F7	U22
IO76NB3F7	U20
IO76PB3F7	T20
IO77NB3F7	R17
IO77PB3F7	P17
IO78NB3F7	W21
IO78PB3F7	W22
IO79NB3F7	T18
IO79PB3F7	R18
IO80NB3F7	W20
IO80PB3F7	V20
IO81NB3F7	U19
IO81PB3F7	T19
IO82NB3F7	U18
IO82PB3F7	V19
IO83NB3F7	R16
IO83PB3F7	P16
Bank 4	
IO84NB4F8	AB18
IO84PB4F8	AB19
IO85NB4F8	T15
IO85PB4F8	T16
IO86NB4F8	AA18
IO86PB4F8	AA19
IO87NB4F8	W17
IO87PB4F8	V17
IO88NB4F8	Y19
IO88PB4F8	W18
IO89NB4F8	U14
IO89PB4F8	U15

FG484	
AX500 Function	Pin Number
IO90NB4F8	Y17
IO90PB4F8	Y18
IO91NB4F8	V15
IO91PB4F8	V16
IO92PB4F8	AB17
IO93NB4F8	Y15
IO93PB4F8	Y16
IO94NB4F9	AA16
IO94PB4F9	AA17
IO95NB4F9	AB14
IO95PB4F9	AB15
IO96NB4F9	W15
IO96PB4F9	W16
IO97NB4F9	AA13
IO97PB4F9	AB13
IO98NB4F9	AA14
IO98PB4F9	AA15
IO100NB4F9	Y14
IO100PB4F9	W14
IO101NB4F9	Y12
IO101PB4F9	Y13
IO102NB4F9	AA11
IO102PB4F9	AA12
IO103NB4F9/CLKEN	V12
IO103PB4F9/CLKEP	V13
IO104NB4F9/CLKFN	W11
IO104PB4F9/CLKFP	W12
Bank 5	
IO105NB5F10/CLKGN	U10
IO105PB5F10/CLKGP	U11
IO106NB5F10/CLKHN	V9
IO106PB5F10/CLKHP	V10
IO107NB5F10	Y10
IO107PB5F10	Y11
IO108NB5F10	AA9

FG484	
AX500 Function	Pin Number
VCCA	P11
VCCA	P12
VCCA	P13
VCCA	T6
VCCA	U17
VCCPLA	F10
VCCPLB	G9
VCCPLC	D13
VCCPLD	G13
VCCPLE	U13
VCCPLF	T14
VCCPLG	W10
VCCPLH	T10
VCCDA	D14
VCCDA	D5
VCCDA	F16
VCCDA	G12
VCCDA	L4
VCCDA	M18
VCCDA	T11
VCCDA	T17
VCCDA	U7
VCCDA	V14
VCCDA	V8
VCCIB0	A3
VCCIB0	B3
VCCIB0	H10
VCCIB0	H11
VCCIB0	H9
VCCIB1	A20
VCCIB1	B20
VCCIB1	H12
VCCIB1	H13
VCCIB1	H14
VCCIB2	C21

FG484	
AX500 Function	Pin Number
VCCIB2	C22
VCCIB2	J15
VCCIB2	K15
VCCIB2	L15
VCCIB3	M15
VCCIB3	N15
VCCIB3	P15
VCCIB3	Y21
VCCIB3	Y22
VCCIB4	AA20
VCCIB4	AB20
VCCIB4	R12
VCCIB4	R13
VCCIB4	R14
VCCIB5	AA3
VCCIB5	AB3
VCCIB5	R10
VCCIB5	R11
VCCIB5	R9
VCCIB6	M8
VCCIB6	N8
VCCIB6	P8
VCCIB6	Y1
VCCIB6	Y2
VCCIB7	C1
VCCIB7	C2
VCCIB7	J8
VCCIB7	K8
VCCIB7	L8
VCOMPLA	D10
VCOMPLB	G10
VCOMPLC	E12
VCOMPLD	G14
VCOMPLE	W13
VCOMPLF	T13

FG484	
AX500 Function	Pin Number
VCOMPLG	V11
VCOMPLH	T9
VPUMP	D17

FG676		FG676		FG676	
AX500 Function	Pin Number	AX500 Function	Pin Number	AX500 Function	Pin Number
IO153PB7F14	M6	GND	A8	GND	L11
IO154NB7F14	K2	GND	AC23	GND	L12
IO154PB7F14	L2	GND	AC4	GND	L13
IO155NB7F14	K3	GND	AD24	GND	L14
IO155PB7F14	L3	GND	AD3	GND	L15
IO156NB7F14	L5	GND	AE2	GND	L16
IO156PB7F14	L4	GND	AE25	GND	L17
IO157NB7F14	L6	GND	AF1	GND	M10
IO157PB7F14	L7	GND	AF13	GND	M11
IO158NB7F15	J1	GND	AF14	GND	M12
IO158PB7F15	K1	GND	AF19	GND	M13
IO159NB7F15	J4	GND	AF26	GND	M14
IO159PB7F15	K4	GND	AF8	GND	M15
IO160NB7F15	H2	GND	B2	GND	M16
IO160PB7F15	J2	GND	B25	GND	M17
IO161NB7F15	K6	GND	B26	GND	N1
IO161PB7F15	K5	GND	C24	GND	N10
IO162NB7F15	H3	GND	C3	GND	N11
IO162PB7F15	J3	GND	G20	GND	N12
IO163NB7F15	G2	GND	G7	GND	N13
IO163PB7F15	G1	GND	H1	GND	N14
IO164NB7F15	G4	GND	H19	GND	N15
IO164PB7F15	H4	GND	H26	GND	N16
IO165NB7F15	F3	GND	H8	GND	N17
IO165PB7F15	G3	GND	J18	GND	N26
IO166NB7F15	E2	GND	J9	GND	P1
IO166PB7F15	F2	GND	K10	GND	P10
IO167NB7F15	F5	GND	K11	GND	P11
IO167PB7F15	G5	GND	K12	GND	P12
Dedicated I/O		GND	K13	GND	P13
GND	A1	GND	K14	GND	P14
GND	A13	GND	K15	GND	P15
GND	A14	GND	K16	GND	P16
GND	A19	GND	K17	GND	P17
GND	A26	GND	L10	GND	P26

FG676	
AX500 Function	Pin Number
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17
VCCIB4	W18
VCCIB4	Y17
VCCIB4	Y18
VCCIB4	Y19
VCCIB5	W10
VCCIB5	W11
VCCIB5	W12
VCCIB5	W13
VCCIB5	W9
VCCIB5	Y10
VCCIB5	Y8
VCCIB5	Y9
VCCIB6	P8
VCCIB6	R8
VCCIB6	T8
VCCIB6	U7
VCCIB6	U8
VCCIB6	V7
VCCIB6	V8
VCCIB6	W7
VCCIB7	H7
VCCIB7	J7
VCCIB7	J8
VCCIB7	K7
VCCIB7	K8

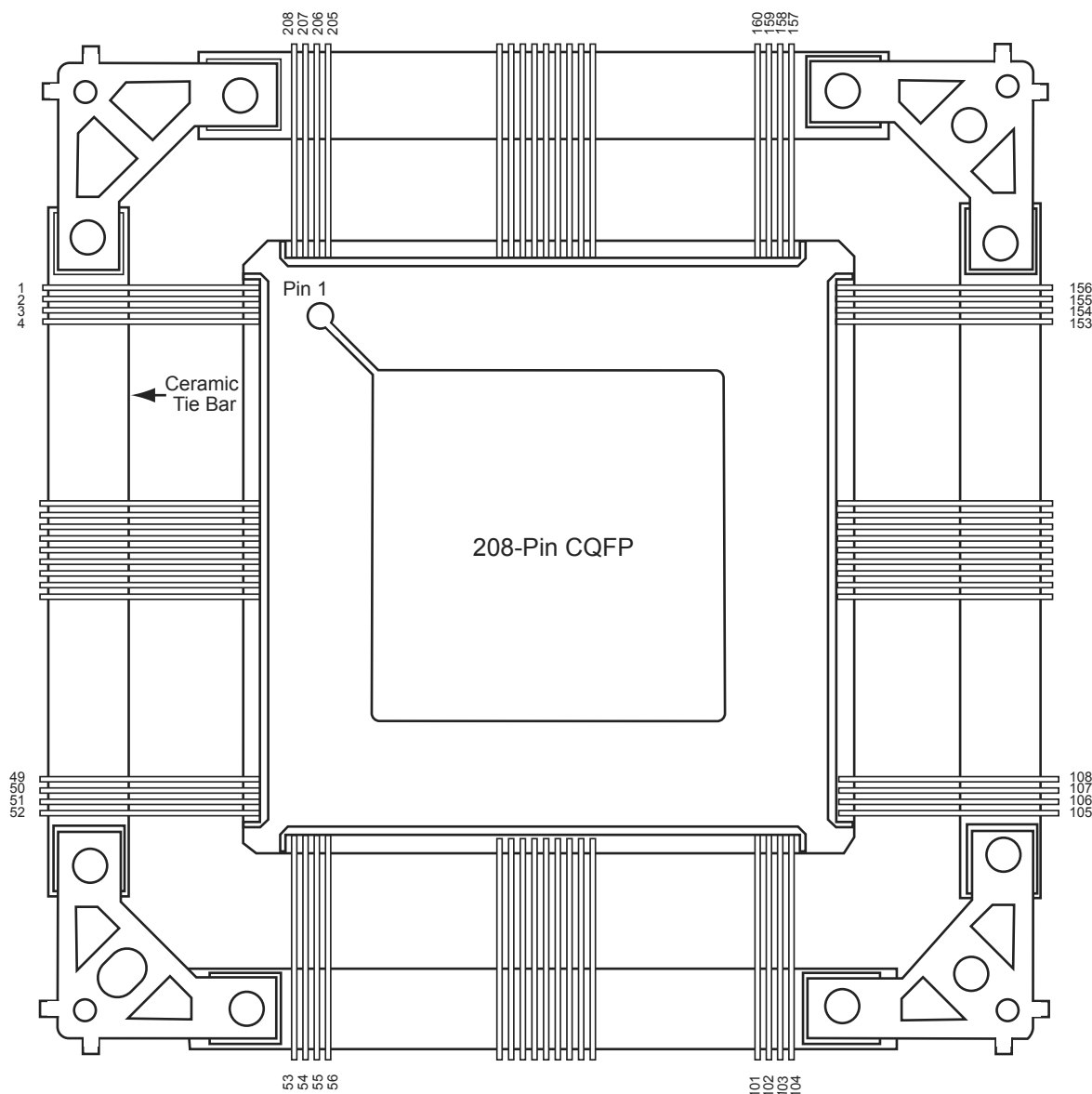
FG676	
AX500 Function	Pin Number
VCCIB7	L8
VCCIB7	M8
VCCIB7	N8
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCOMPLA	D12
VCOMPLB	G13
VCOMPLC	D15
VCOMPLD	F14
VCOMPLE	AD15
VCOMPLF	AB14
VCOMPLG	AD12
VCOMPLH	Y13
VPUMP	E22

FG676	
AX1000 Function	Pin Number
NC	D13
NC	D14
PRA	E13
PRB	B14
PRC	Y14
PRD	AD14
TCK	E5
TDI	B3
TDO	G6
TMS	D4
TRST	A2
VCCA	AB4
VCCA	AF24
VCCA	C1
VCCA	C26
VCCA	J10
VCCA	J11
VCCA	J12
VCCA	J13
VCCA	J14
VCCA	J15
VCCA	J16
VCCA	J17
VCCA	K18
VCCA	K9
VCCA	L18
VCCA	L9
VCCA	M18
VCCA	M9
VCCA	N18
VCCA	N9
VCCA	P18
VCCA	P9
VCCA	R18
VCCA	R9
VCCA	T18

FG676	
AX1000 Function	Pin Number
VCCA	T9
VCCA	U18
VCCA	U9
VCCA	V10
VCCA	V11
VCCA	V12
VCCA	V13
VCCA	V14
VCCA	V15
VCCA	V16
VCCA	V17
VCCPLA	E12
VCCPLB	F13
VCCPLC	E15
VCCPLD	G14
VCCPLE	AF15
VCCPLF	AA14
VCCPLG	AF12
VCCPLH	AB13
VCCDA	A11
VCCDA	A3
VCCDA	AB22
VCCDA	AB5
VCCDA	AD10
VCCDA	AD11
VCCDA	AD13
VCCDA	AD16
VCCDA	AD17
VCCDA	B1
VCCDA	B11
VCCDA	B17
VCCDA	C16
VCCDA	D24
VCCDA	E14
VCCDA	P2
VCCDA	P23

FG676	
AX1000 Function	Pin Number
VCCIB0	G10
VCCIB0	G8
VCCIB0	G9
VCCIB0	H10
VCCIB0	H11
VCCIB0	H12
VCCIB0	H13
VCCIB0	H9
VCCIB1	G17
VCCIB1	G18
VCCIB1	G19
VCCIB1	H14
VCCIB1	H15
VCCIB1	H16
VCCIB1	H17
VCCIB1	H18
VCCIB2	H20
VCCIB2	J19
VCCIB2	J20
VCCIB2	K19
VCCIB2	K20
VCCIB2	L19
VCCIB2	M19
VCCIB2	N19
VCCIB3	P19
VCCIB3	R19
VCCIB3	T19
VCCIB3	U19
VCCIB3	U20
VCCIB3	V19
VCCIB3	V20
VCCIB3	W20
VCCIB4	W14
VCCIB4	W15
VCCIB4	W16
VCCIB4	W17

CQ208



Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.microsemi.com/soc/products/rescenter/package/index.html>.

CQ256		CQ256		CQ256	
AX2000 Function	Pin Number	AX2000 Function	Pin Number	AX2000 Function	Pin Number
IO242NB5F22	74	IO315PB7F29	21	GND	121
IO242PB5F22	75	IO316NB7F29	18	GND	128
IO243NB5F22	70	IO316PB7F29	19	GND	129
IO243PB5F22	71	IO317NB7F29	14	GND	132
IO244NB5F22	68	IO317PB7F29	15	GND	139
IO244PB5F22	69	IO318NB7F29	12	GND	145
Bank 6		IO318PB7F29	13	GND	151
IO257PB6F24	60	IO320NB7F29	8	GND	157
IO258NB6F24	58	IO320PB7F29	9	GND	161
IO258PB6F24	59	Bank 7		GND	165
Bank 6		IO341NB7F31	6	GND	171
IO279NB6F26	56	IO341PB7F31	7	GND	177
IO279PB6F26	57	Dedicated I/O		GND	183
IO280NB6F26	52	GND	1	GND	190
IO280PB6F26	53	GND	5	GND	192
IO281NB6F26	50	GND	11	GND	193
IO281PB6F26	51	GND	17	GND	201
IO282NB6F26	46	GND	23	GND	207
IO282PB6F26	47	GND	29	GND	213
IO284NB6F26	44	GND	33	GND	219
IO284PB6F26	45	GND	37	GND	225
IO285NB6F26	40	GND	43	GND	231
IO285PB6F26	41	GND	49	GND	239
IO286NB6F26	38	GND	55	GND	245
IO286PB6F26	39	GND	62	GND	256
IO287NB6F26	34	GND	64	PRA	227
IO287PB6F26	35	GND	65	PRB	226
Bank 7 9		GND	73	PRC	99
IO310NB7F29	30	GND	79	PRD	98
IO310PB7F29	31	GND	85	TCK	253
IO311NB7F29	26	GND	91	TDI	252
IO311PB7F29	27	GND	97	TDO	250
IO312NB7F29	24	GND	103	TMS	254
IO312PB7F29	25	GND	109	TRST	255
IO315NB7F29	20	GND	115	VCCA	3

CQ352	
AX250 Function	Pin Number
IO64PB4F4	167
IO65NB4F4	170
IO65PB4F4	171
IO66NB4F4	164
IO66PB4F4	165
IO67NB4F4	160
IO67PB4F4	161
IO68NB4F4	158
IO68PB4F4	159
IO70NB4F4	154
IO70PB4F4	155
IO72NB4F4	152
IO72PB4F4	153
IO73NB4F4	146
IO73PB4F4	147
IO74NB4F4/CLKEN	142
IO74PB4F4/CLKEP	143
IO75NB4F4/CLKFN	136
IO75PB4F4/CLKFP	137
Bank 5	
IO76NB5F5/CLKGN	128
IO76PB5F5/CLKGP	129
IO77NB5F5/CLKHN	122
IO77PB5F5/CLKHP	123
IO78NB5F5	112
IO78PB5F5	113
IO79NB5F5	118
IO79PB5F5	119
IO80NB5F5	110
IO80PB5F5	111
IO82NB5F5	106
IO82PB5F5	107
IO84NB5F5	100
IO84PB5F5	101
IO85NB5F5	104

CQ352	
AX250 Function	Pin Number
IO85PB5F5	105
IO86NB5F5	98
IO86PB5F5	99
IO87NB5F5	94
IO87PB5F5	95
IO89NB5F5	92
IO89PB5F5	93
Bank 6	
IO90PB6F6	86
IO91NB6F6	84
IO91PB6F6	85
IO92NB6F6	78
IO92PB6F6	79
IO93NB6F6	82
IO93PB6F6	83
IO95NB6F6	76
IO95PB6F6	77
IO96NB6F6	72
IO96PB6F6	73
IO97NB6F6	70
IO97PB6F6	71
IO98NB6F6	66
IO98PB6F6	67
IO99NB6F6	64
IO99PB6F6	65
IO100NB6F6	60
IO100PB6F6	61
IO101NB6F6	58
IO101PB6F6	59
IO103NB6F6	54
IO103PB6F6	55
IO104NB6F6	52
IO104PB6F6	53
IO105NB6F6	48
IO105PB6F6	49

CQ352	
AX250 Function	Pin Number
IO106NB6F6	46
IO106PB6F6	47
Bank 7	
IO107NB7F7	40
IO107PB7F7	41
IO108NB7F7	42
IO108PB7F7	43
IO109NB7F7	36
IO109PB7F7	37
IO110NB7F7	34
IO110PB7F7	35
IO111NB7F7	30
IO111PB7F7	31
IO113NB7F7	28
IO113PB7F7	29
IO114NB7F7	24
IO114PB7F7	25
IO115NB7F7	22
IO115PB7F7	23
IO116NB7F7	18
IO116PB7F7	19
IO117NB7F7	16
IO117PB7F7	17
IO118NB7F7	12
IO118PB7F7	13
IO119NB7F7	10
IO119PB7F7	11
IO121NB7F7	6
IO121PB7F7	7
IO123NB7F7	4
IO123PB7F7	5
Dedicated I/O	
GND	1
GND	9
GND	15

CG624	
AX2000 Function	Pin Number
IO310NB7F29	N10
IO310PB7F29	N9
IO311NB7F29	K1
IO311PB7F29	L1
IO313NB7F29	M5
IO316NB7F29	L6
IO316PB7F29	L5
IO317NB7F29	K2
IO317PB7F29	L2
IO318NB7F29	K4
IO318PB7F29	L4
IO320NB7F29	J3
IO321NB7F30	J2
IO321PB7F30	J1
IO323NB7F30	L7
IO323PB7F30	M7
IO324NB7F30	M9
IO324PB7F30	M8
IO327NB7F30	F1
IO327PB7F30	G1
IO328NB7F30	K7
IO328PB7F30	K6
IO329NB7F30	D1
IO329PB7F30	E1
IO331PB7F30	G2
IO332NB7F31	H3
IO332PB7F31	H2
IO333NB7F31	E2
IO333PB7F31	F2
IO334NB7F31	H4
IO334PB7F31	J4
IO335NB7F31	H5

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
IO335PB7F31	H6
IO337NB7F31	D2
IO338NB7F31	J6
IO338PB7F31	J5
IO339NB7F31	F3
IO339PB7F31	E3
IO340NB7F31	G4*
IO340PB7F31	G3*
IO341NB7F31	K8
IO341PB7F31	L8
Dedicated I/O	
GND	K5
GND	A18
GND	A2
GND	A24
GND	A25
GND	A8
GND	AA10
GND	AA16
GND	AA18
GND	AA21
GND	AA5
GND	AB22
GND	AB4
GND	AC10
GND	AC16
GND	AC23
GND	AC3
GND	AD1
GND	AD2
GND	AD24
GND	AD25

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
GND	AE1
GND	AE18
GND	AE2
GND	AE24
GND	AE25
GND	AE8
GND	B1
GND	B2
GND	B24
GND	B25
GND	C10
GND	C16
GND	C23
GND	C3
GND	D22
GND	D4
GND	E10
GND	E16
GND	E21
GND	E5
GND	E8
GND	H1
GND	H21
GND	H25
GND	K21
GND	K23
GND	K3
GND	L11
GND	L12
GND	L13
GND	L14
GND	L15

Note: *Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.

CG624	
AX2000 Function	Pin Number
VCCIB2	D23
VCCIB2	E22
VCCIB2	K17
VCCIB2	L17
VCCIB2	M16
VCCIB3	AA22
VCCIB3	AB23
VCCIB3	AC24
VCCIB3	AC25
VCCIB3	P16
VCCIB3	R17
VCCIB3	T17
VCCIB4	AB21
VCCIB4	AC22
VCCIB4	AD23
VCCIB4	AE23
VCCIB4	T14
VCCIB4	U15
VCCIB4	U16
VCCIB5	AB5
VCCIB5	AC4
VCCIB5	AD3
VCCIB5	AE3
VCCIB5	T12
VCCIB5	U10
VCCIB5	U11
VCCIB6	AA4
VCCIB6	AB3
VCCIB6	AC1
VCCIB6	AC2
VCCIB6	P10
VCCIB6	R9

Note: **Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

CG624	
AX2000 Function	Pin Number
VCCIB6	T9
VCCIB7	C1
VCCIB7	C2
VCCIB7	D3
VCCIB7	E4
VCCIB7	K9
VCCIB7	L9
VCCIB7	M10
VCCPLA	E12
VCCPLB	J12
VCCPLC	E14
VCCPLD	H14
VCCPLE	Y14
VCCPLF	U14
VCCPLG	Y12
VCCPLH	U12
VCOMPLA	F12
VCOMPLB	H12
VCOMPLC	F14
VCOMPLD	J14
VCOMPLE	AA14
VCOMPLF	V14
VCOMPLG	AA12
VCOMPLH	V12
VPUMP	E20

Note: **Not routed on the same package layer and to adjacent LGA pads as its differential pair complement. Recommended to be used as a single-ended I/O.*

Revision	Changes	Page
Revision 3 (continued)	The timing characteristics tables from pages 2-26 to 2-60 were updated.	2-26 to 2-60
	The "Global Resources" section was updated.	2-66
	The timing characteristics tables from pages 2-102 to 2-103 were updated.	2-102 to 2-103
	The "PQ208", "FG256", and "FG324" tables are new.	3-9,3-16, 3-84